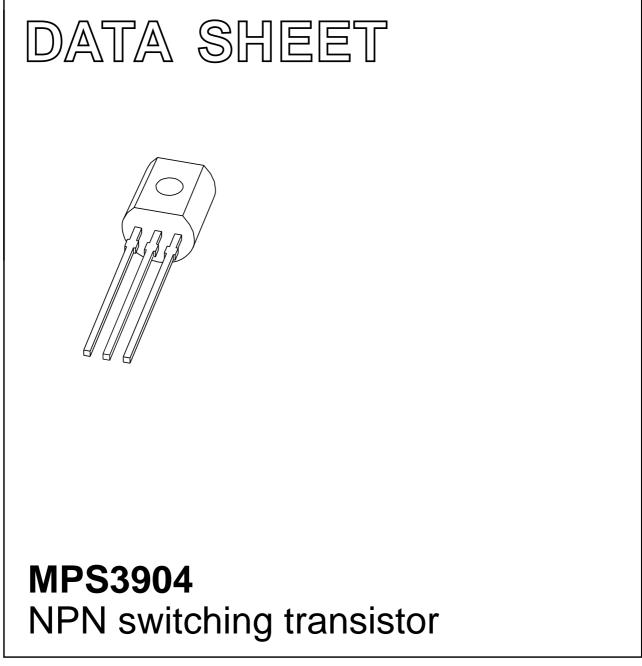
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1999 Apr 12 2004 Oct 11



### MPS3904

#### FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 40 V).

#### APPLICATIONS

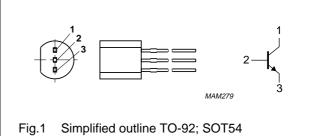
• General purpose switching and amplification.

#### DESCRIPTION

NPN transistor in a TO-92; SOT54 plastic package. PNP complement: MPS3906.

#### PINNING

PIN	DESCRIPTION	
1	collector	
2	base	
3	emitter	



and symbol.

#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE			
	NAME	DESCRIPTION	VERSION		
MPS3904	SC-43A	43A plastic single-ended leaded (through hole) package; 3 leads			

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	6	V
I <sub>C</sub>	collector current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		-	200	mA
I <sub>BM</sub>	peak base current		_	200	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$	-	500	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

### MPS3904

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	250	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### CHARACTERISTICS

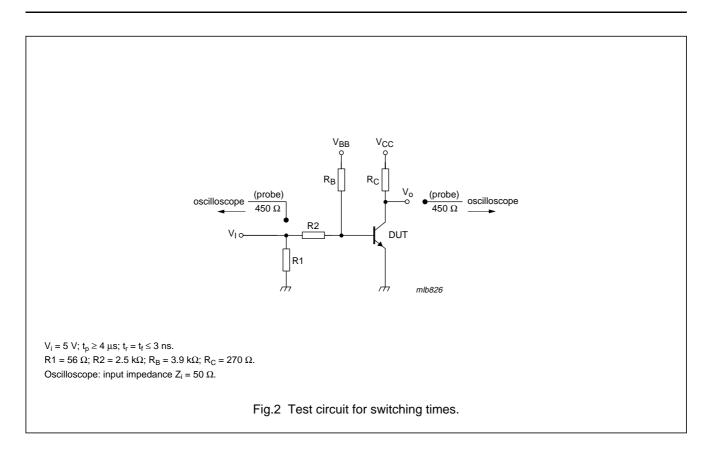
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 30 V; I <sub>E</sub> = 0 A	-	50	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A	-	50	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 1 V; note 1			
		$I_{\rm C} = 0.1  {\rm mA}$	40	_	
		$I_{\rm C} = 1  \rm{mA}$	70	_	
		I <sub>C</sub> = 10 mA	100	300	
		I <sub>C</sub> = 50 mA	60	_	
		I <sub>C</sub> = 100 mA	30	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_{C} = 10 \text{ mA}; I_{B} = 1 \text{ mA}; \text{ note } 1$	_	200	mV
		$I_{C} = 50 \text{ mA}; I_{B} = 5 \text{ mA}; \text{ note } 1$	_	300	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_{C} = 10 \text{ mA}; I_{B} = 1 \text{ mA}; \text{ note } 1$	650	850	mV
		$I_{C} = 50 \text{ mA}; I_{B} = 5 \text{ mA}; \text{ note } 1$	_	950	mV
C <sub>c</sub>	collector capacitance	$V_{CB} = 5 \text{ V}; \text{ I}_{E} = \text{i}_{e} = 0 \text{ A};$ f = 100 kHz to 1 MHz	-	5	pF
C <sub>e</sub>	emitter capacitance	$V_{EB} = 0.5 \text{ V}; I_{C} = i_{c} = 0 \text{ A};$ f = 100 kHz to 1 MHz	-	15	pF
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = 20 V; I <sub>C</sub> = 10 mA; f = 100 MHz	180	-	MHz
F	noise figure	$V_{CE} = 5$ V; I <sub>C</sub> = 100 μA; R <sub>S</sub> = 1 kΩ; f = 10 Hz to 15.7 kHz	-	5	dB
Switching t	imes (between 10 % and 90 % level	s); (see Fig.2)	•		•
t <sub>on</sub>	turn-on time	$I_{Con} = 10 \text{ mA}; I_{Bon} = 1 \text{ mA}; I_{Boff} = -1 \text{ mA};$	_	110	ns
t <sub>d</sub>	delay time	$V_{CC} = 3 \text{ V}; \text{ V}_{BB} = -1.9 \text{ V}$	-	50	ns
t <sub>r</sub>	rise time	1	_	60	ns
t <sub>off</sub>	turn-off time	1	-	1200	ns
t <sub>s</sub>	storage time	1	-	1000	ns
t <sub>f</sub>	fall time	1	_	200	ns

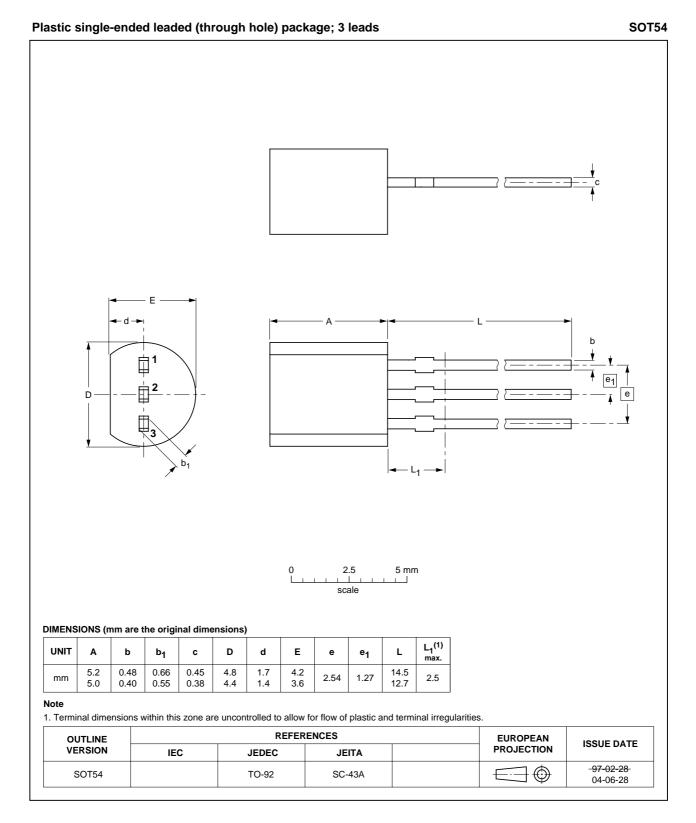
#### Note

1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta = 0.02.$ 

### MPS3904



#### PACKAGE OUTLINE



MPS3904

MPS3904

#### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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